

Micro Stamping Technology



The requirements made on Micro-Electro-Mechanical Systems (MEMS) and sensors are constantly rising. Particularly, in the case of electronic components, increasingly complex functions are being brought together in smaller and smaller spaces.

With innovative micro-stamping concepts, we offer customer-oriented solutions as well as technologically demanding products and processing equipment close to the limits of feasibility.

- Core competence high precision stamping
- Structures down to 60 μm
- Material thickness down to 40 μm
- Smallest radius 50 μm
- Highest demands on tooling technology
- Extensive materials know how

→ Realized at Heraeus in “reel to reel” mass production already

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